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		Application Number	09/910,914		
		Filing Date	July 24, 2001		
		First Named Inventor	Kie Y. Ahn		
		Group Art Unit	<del>NA</del> 2823		
		Examiner Name	Not Yet Assigned		
Sheet	1	of	1	Attorney Docket Number	M4065.0461/P461

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
8F	A	"Current and Future Low-k Dielectrics for Cu Interconnects" by Takamaro Kikkawa, 2000 IEEE, Pages 253-256	
8F	B	"Atomic Layer Deposition of Tungsten Nitride Films Using Sequential Surface Reactions" by J.W. Klaus, et al, Journal of The Electrochemical Society, 2000, Pages 1175-1181.	
8F	C	"Copper electroless deposition technology of ultra-large-scale-integration (ULSI) metallization" by Yosi Shacham-Diamond, et al., Elsevier Science, 1997, Pages 47-58.	
8F	D	"Blanket and Selective Cooper CVD From Cu(FOD)2 for Multilevel Metallization" by Alain E. Kaloyeros, et al, Materials Research Society, Vol. 181, 1990, Pages 79-84.	

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